Guidelines for the Manuscript Preparation for the 2nd International Conference on Cat-CVD (Hot-Wire CVD) Process

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Abstract
This paper contains instructions for preparing your manuscript for the 2nd International Conference on Cat-CVD (Hot-Wire CVD) Process, which will be published in a special edition of Thin Solid Films. Please have 3 copies of your manuscript prepared and ready to hand in when you check in at the registration desk. See Table 1 for a timeline of the manuscript submission and life cycle with action due dates for authors highlighted. Please follow these guidelines exactly. Each paper should have an abstract of ~100 words summarizing the important results and conclusions.

Keywords
Instructions, Guidelines, Manuscript
A maximum of four keywords should be indicated below the abstract to describe the contents of the manuscript. Keywords should be selected, if appropriate, from the following classes: theoretical methods, experimental methods, phenomena, materials, and applications. Examples of keywords used by the papers from the previous conference include Catalytic chemical vapor deposition; Silicon wafer; Gallium arsenide wafer; Low temperature epitaxial growth; Etching; Catalytic CVD; Surface modification; Oxidation; Hot-wire deposition; Amorphous materials; Deposition process; Solar cells; Heterostructures. This list may also be obtained from http://authors.elsevier.com/JournalDetail.html?PubID=504106&Precis=KIND.

Main Text
Please adhere to the following order:
Title, Authors, Affiliations, Abstract, Keywords (as illustrated above)
Main text
- Introduction
- Experimental Details
- Results
- Discussion

Acknowledgements
Appendix
References
List of table and figure captions
Tables
Figures

Some flexibility of presentation of the main text will be allowed but the authors are urged to arrange the subject matter clearly under such headings as Introduction, Experimental Details, Results, Discussion, etc. For example combining Results and Discussion into one heading, use of subsections, etc. The sections and subsections should be numbered 1., 1.1, …, 2., …

1. Manuscript preparation

1.1. Manuscript format

Copies of the manuscript should be submitted in double-spaced 12-pt serif font (e.g. New Times Roman) on single-column, single sided, numbered pages of uniform size with a wide margin on the left and bottom. Leave a blank line between each paragraph. This document is formatted with the same requirements as an example of how to prepare your final manuscript.

1.2. Manuscript length

Your manuscript should be limited to 4 pages for contributed papers and 6 for invited papers. As a guideline, 850 words for full two-column page (single spaced) and four illustrations per page may be used to calculate its length (i.e., 1/4 page per figure/table). NOTE: this manuscript is longer than the average double-spaced conference handout.

1.3. Data to share

Since this is a processing conference, please share as much detail about your processing conditions as possible. Specifically,

- Filament material
- Filament shape
- Filament size (e.g., diameter)
- Filament geometry
- Filament to substrate spacing
- Filament temperatures
- Filament power (AC, DC)
- Pressure ranges
- Gas flow rates
- Substrate temperatures
- Substrate materials
- Deposition rates
- anything unique or special about your process

The more we share this information, the better information will flow between participants and those who read the final conference proceedings.

2. Language

Papers will be published in either American or British English. It is expected that authors submit carefully written and proofread material meeting the standards of scientific publication. It is recommended that non-English speaking authors have their work edited and proofread by someone fluent in English before submission of their paper

3. Bibliographic references and notes

References should be numbered consecutively (numerals in square brackets) throughout the text and collected together with the footnotes in a reference list at the end of the paper. In the text, references are noted by on-line Arabic numerals in square brackets as in: "Smith and Roberts [1] measured…" These reference indicators should be one space from words and inside punctuation: "… some previous work [1,3,5-7]." Avoid references that are not in readily accessible reports.

List all authors. Journal titles should be abbreviated according to the Chemical Abstracts Service Source Index, 1970 edition, and supplements. Leave a blank line between each entry in the list of references. See the reference section for examples of how to format references from various sources.

4. Illustrations (Figures and Tables)

Do not embed figures and/or tables in text. Illustration and table captions must be submitted with the manuscript in a separate list and on a separate sheet. All tables and illustrations should be numbered consecutively throughout the paper using Arabic numerals. (Examples: Fig. 1. and Table 1). All illustrations should be provided in separate files and as hardcopy on separate sheets.

Line drawings should be high-contrast laser printouts. Use dark black ink on high-quality opaque white paper. Avoid tracing and textured papers. Line drawings should preferably all require the same degree of reduction, and should be submitted on paper of the same size as, or smaller than, the main text to prevent damage in transit.

Illustrations must fit a one- or two-column format (8.25 or 17.75 cm overall width) on the journal page, the one-column format being preferred. Make sure to use uniform lettering and sizing of your original artwork. It is preferred you use a sans serif font (e.g., Arial) in your figures. Please submit the line drawings in the actual size. Original illustrations that do not need to be reduced will yield the best quality. Once reduced, all characters within an illustration should be at least 1.5 mm height. Ensure that nothing is hand-drawn or hand-labeled in your figures. Compare Fig. 1 to Fig. 2 to see the contrast between an acceptable (clean) figure and an unacceptable (cluttered) figure.

For micrographs and other photographs, please provide glossy prints clearly identified on the back with the figure number.

5. Color illustrations

Photographs should be submitted as clear black-and white prints on glossy paper. However, illustrations can be printed in color when they are judged by the Editor to be essential to the presentation. The publisher and author will each bear part of the extra costs involved.

Acknowledgements

The authors would like to thank Elesevier and the editor of Thin Solid Films for agreeing to publish our proceedings as well as Hedeki Matusmura for his exemplary leadership in the 1st International Conference on Cat-CVD (Hot-Wire CVD) Process in Kanazawa Japan. This work was funded by XYZ.

Appendix

Include anything that is too large for discussion in the main text and is of limited interest to a general audience.

References

Journal papers sample references

1. D. Brandl, Ch. Schoppmann, Ch. Tomaschko, H. Voit, Thin Solid Films 242 (1995) 192.
2. A. Erdemir, C. Bindal, J. Pagan, P. Wilbur, Surf. Coat. Technol. 76/77 (1995) 559.
3. S. Auzary, K.F. Badawi, L. Bimbault, J. Rabier, R.J. Gaboriaud, P. Goudeau, J. Phys. III 7 (1997) 35 (in French).
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Electronic publications sample references

5. F. Yu, X.-S. Wu, Phys. Rev. Lett. 68 (1992) 2996. hep-th/9112009.

Thesis (if available through a library) sample references

6. R. Ramesh, Ph.D. Thesis, College van Dekanen, University of Twente, The Netherlands, 1992.

Monographs, edited books sample references

7. J.L. Vosson, W. Kern, Thin Films Processes, Academic Press, New-York NY, 1987.
8. M.J. Carr, C.E. Lymar, J.M. Cowley, In: J.M. Cowley (Ed.), Electron Diffraction Technique, vol. 1, International Union of Crystallography/Oxford University Press, New York, 1992, p. 122.
9. M.J. Adams, B.J. Briscoe, S.K. Sinha, in: D. Dowson, C.M. Taylor, T.H.C. Childs, M. Godet, G. Dalmas (Eds.), Dissipative Processes in Tribology, Tribology Series, vol. 27, Elsevier, Amsterdam, 1994, p.223.

Conference Proceedings sample references

10. C.H. Perry, F. Lu, F. Namavar, N.M. Kalkhoran, R.A. Soref, in: S.S.Iyer, R.T. Collins, L.T. Canham (Eds.), Light Emission from Silicon, Boston, U.S.A., December 3-5, 1991, Materials Research Society Symposium Proceeding 256 (1991) 153.
11. P. Hones, R. Sanjinés, F. Lévy, in: B.D. Sartwell, J.H. Givens, C. Mitterer, S.L. Rohde (Eds.), 25th International Conference on Metallurgical Coatings and Thin Films, San Diego, U.S.A., April 27-May 1, 1998, Thin Solid Films 332 (1998) 240.
12. J.J. Favier, D. Camel, in: B. Cockayne, J.H.C. Hogg, B. Lunn, P.J. Wright (Eds.), Crystal Growth 1986, Proceedings of the Eight International Conference on Crystal Growth, York, U.K., July 13-18, 1986, p. 50.

Patent sample references

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Industrial reports and papers sample references

14. J. Cleveland, Spring Constant Update, Digital Instruments, Santa Barbara, CA, 1996. add web site address if available

For specific data sample references

15. O.S. Heavens, Optical Properties of Thin Solid Films, Dover, New-York, 1991, p. 46.
16. Powder Diffraction File, Joint Committee on Powder Diffraction Standards, ASTM, Philadelphia, PA, 1967, Card 4301027.

For unpublished results sample references

17. A. Roberts, S.M. Lanoix, unpublished if not accepted for publication, subject to editor's approbation
18. D. H. Smith, Physics Department, Chicago University, Chicago, U.S.A., private commun.

List of table and figure captions

Table 1 Timeline, due date, and life cycle of manuscript submissions

Fig. 1 Example of a clean figure. Note how the eye is drawn to the data rather than the supporting information relative to Fig. 2.

Fig. 2 Example of a cluttered figure. Please avoid using dark grid lines, large keys, and excessive lettering. Long descriptions should go in the caption, not the figure.

Table 1

Date	Description	Action
9/10/02	Manuscript due at conference. Only manuscripts turned in at the conference will be published.	Turn in three (3) copies of the manuscript; one for editor and one for two referees.
10/10/02	Referees must have the manuscripts they are refereeing returned to editor.	
10/15/02	Editor will return refereed manuscripts to authors.	
11/15/02	Final manuscript due to editor with changes/corrections made by author.	Authors must appropriately incorporate changes recommended by referees into a final manuscript.
2/1/03	Editor forwards manuscripts to publisher.	

The editor is Ruud Schropp, Utrecht University, Debye Institute, P.O. Box 80,000, 3508 TA Utrecht, The Netherlands

Figure 1

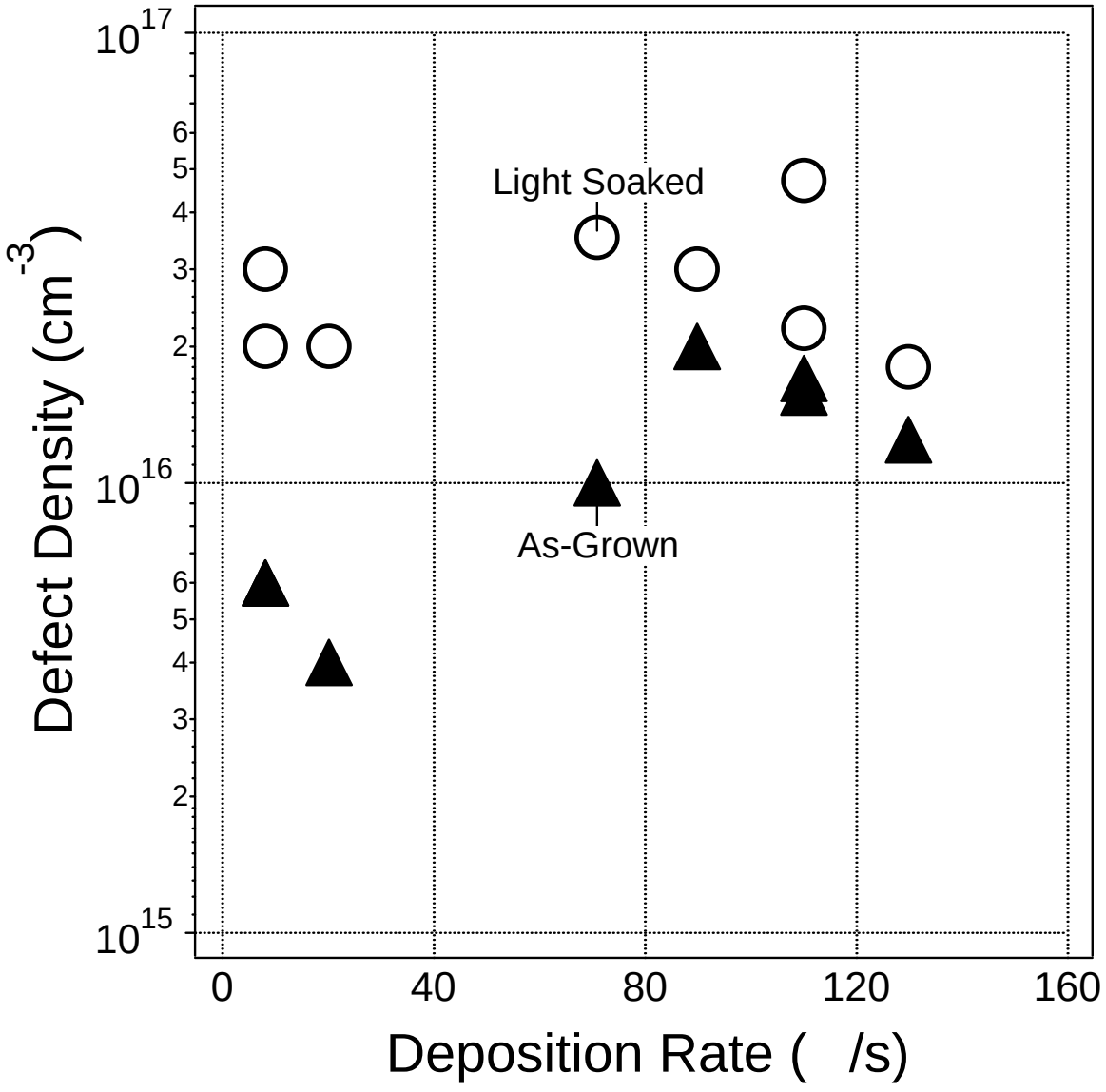
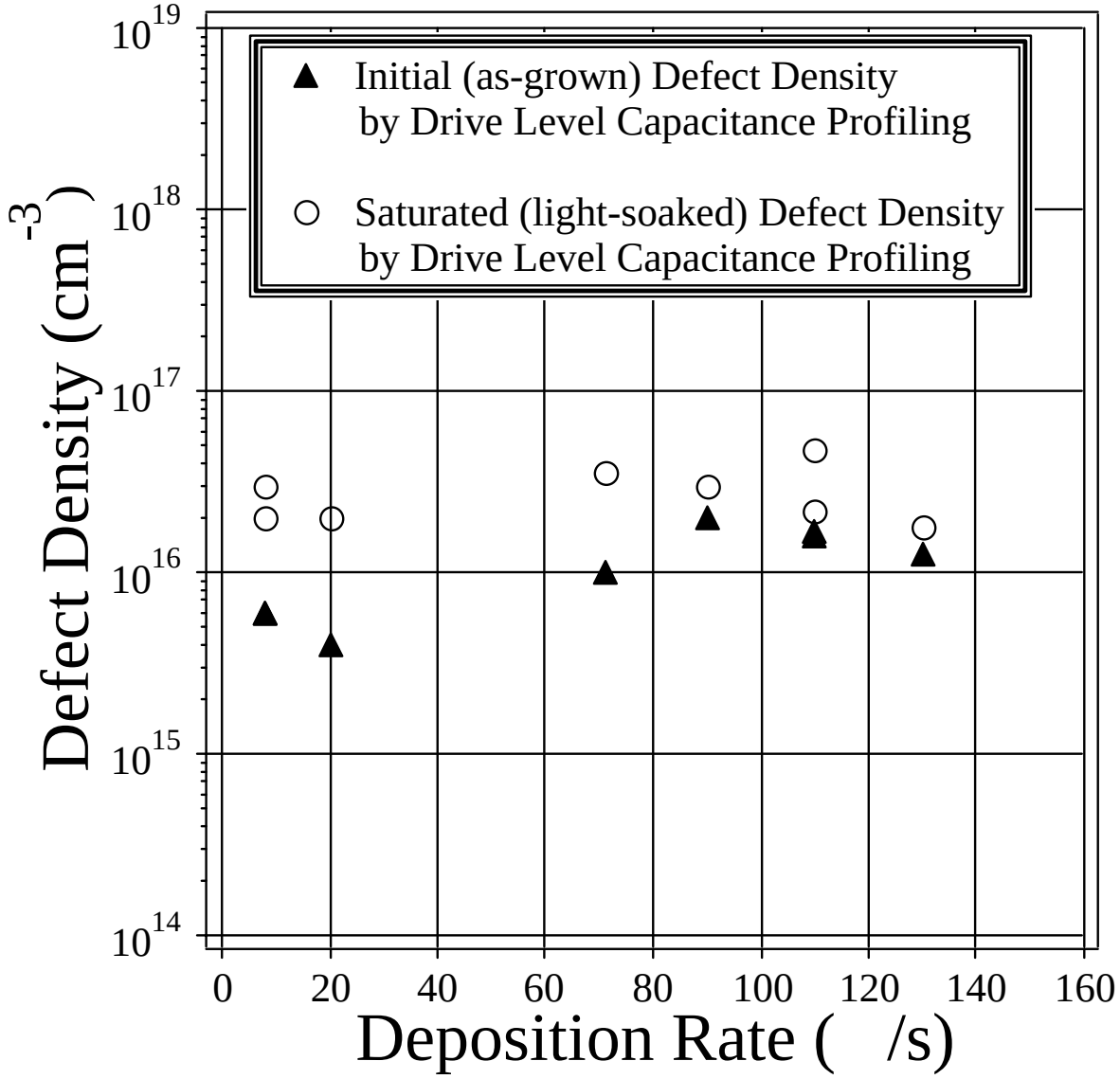

Defect Density (cm-3)
Deposition Rate (/s)
Light Soaked
As-Grown
10^17
10^16
10^15
0
40
80
120
160

Figure 2


Initial (as-grown) Defect Density
by Drive Level Capacitance Profiling
Saturated (light-soaked) Defect Density
by Drive Level Capacitance Profiling
Defect Density (cm-3)
Deposition Rate (/s)
10^19
10^18
10^17
10^16
10^15
10^14
0
20
40
60
80
100
120
140
160